

NR9-1500PY – run sheet

Futurrex, Inc.

nanyte.com/photoresists/nr9-1500py · last updated 2026-07-26

Thickness: 1.2–3 μm

Softbake: 150 °C · 60 s · hotplate

Exposure dose: 190 mJ/cm² @ 365 nm

Post-exposure bake: 100 °C · 60 s

Develop: Developer Resist Developer RD6 · Time 12 s · Rinse
Deionized water rinse until water resistivity reaches prescribed
limit (Processing step 7).